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# SUM110N08-07P

Vishay Siliconix

## N-Channel 75 V (D-S) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
75	0.007 at V <sub>GS</sub> = 10 V	110 <sup>d</sup>	69

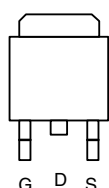
### FEATURES

- TrenchFET<sup>®</sup> Power MOSFETS
- 100 % R<sub>g</sub> and UIS Tested
- Material categorization:  
For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT

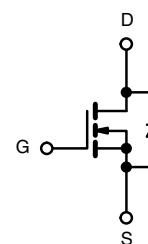
TO-263



Top View

### APPLICATIONS

- Synchronous Rectification



N-Channel MOSFET

Ordering Information: SUM110N08-07P-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	75	V
Gate-Source Voltage		V <sub>GS</sub>	± 20	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	110 <sup>d</sup>	A
	T <sub>C</sub> = 70 °C		103	
Pulsed Drain Current		I <sub>DM</sub>	180	
Avalanche Current		I <sub>AS</sub>	50	
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	125	mJ
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	P <sub>D</sub>	208.3 <sup>b</sup>	W
	T <sub>A</sub> = 25 °C <sup>c</sup>		3.75	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) <sup>c</sup>		R <sub>thJA</sub>	40	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.6	

Notes:

- Duty cycle ≤ 1 %.
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR-4 material).
- Package limited.

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SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>DS</sub> = 0 V, I <sub>D</sub> = 250 μA	75			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5		4.5	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V			± 250	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V			1	μA
		V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
		V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 10 V, V <sub>GS</sub> = 10 V	70			A
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0057	0.0070	Ω
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0092	0.0112	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		43		S
<b>Dynamic<sup>b</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V, f = 1 MHz		4250		pF
Output Capacitance	C <sub>oss</sub>			580		
Reverse Transfer Capacitance	C <sub>rss</sub>			230		
Total Gate Charge <sup>c</sup>	Q <sub>g</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A		69	105	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			23		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			21		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.2	2.4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 30 V, R <sub>L</sub> = 0.6 Ω I <sub>D</sub> ≅ 50 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1 Ω		17	30	ns
Rise Time <sup>c</sup>	t <sub>r</sub>			5	10	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			22	40	
Fall Time <sup>c</sup>	t <sub>f</sub>			6	15	
<b>Source-Drain Diode Ratings and Characteristics T<sub>C</sub> = 25 °C<sup>b</sup></b>						
Continuous Current	I <sub>S</sub>				110	A
Pulsed Current	I <sub>SM</sub>				180	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		0.83	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 75 A, di/dt = 100 A/μs		65	100	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			2.5	5	A
Reverse Recovery Charge	Q <sub>rr</sub>			85	150	nC

Notes:

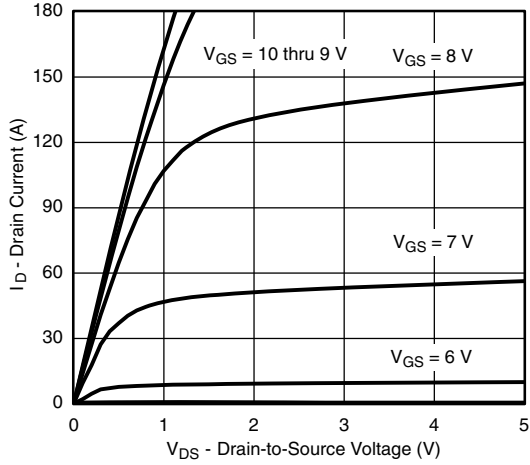
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

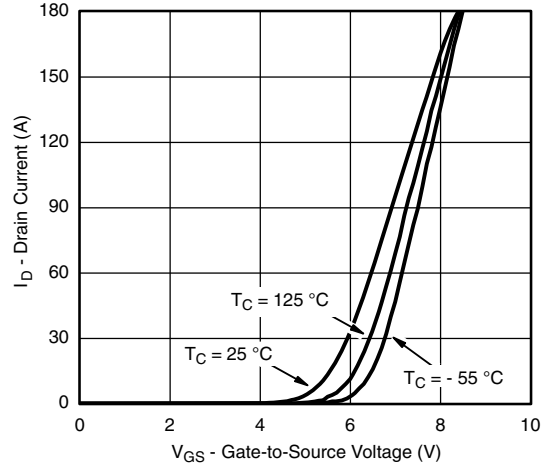


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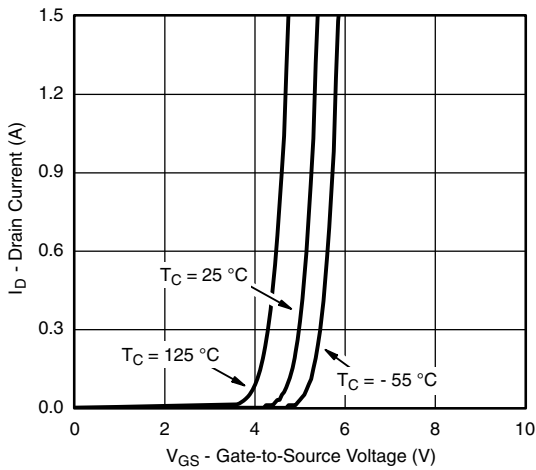
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



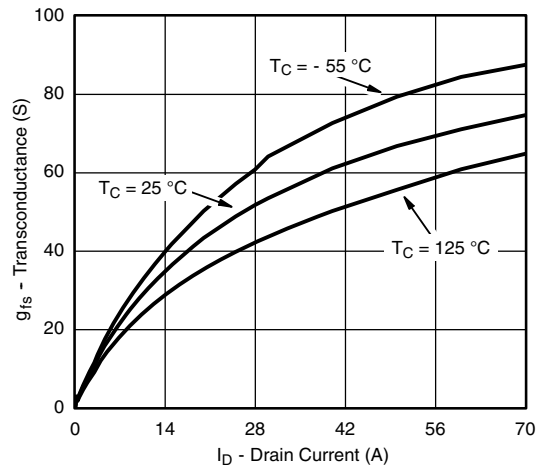
**Output Characteristics**



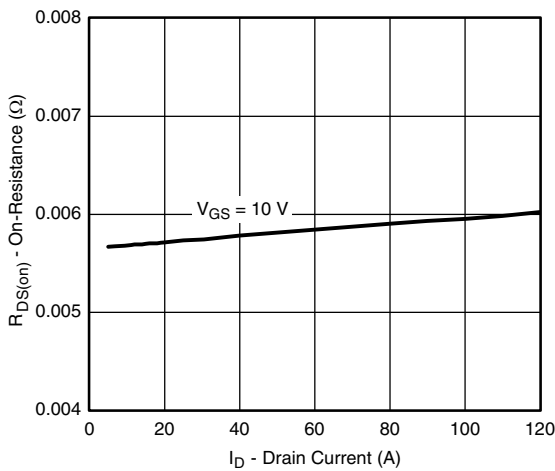
**Transfer Characteristics**



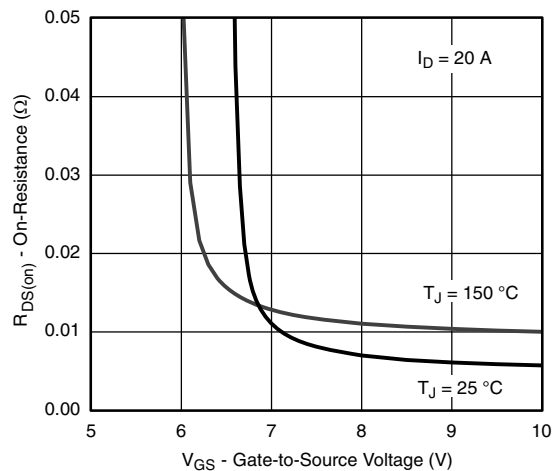
**Transfer Characteristics**



**Transconductance**



**On-Resistance vs. Drain Current**



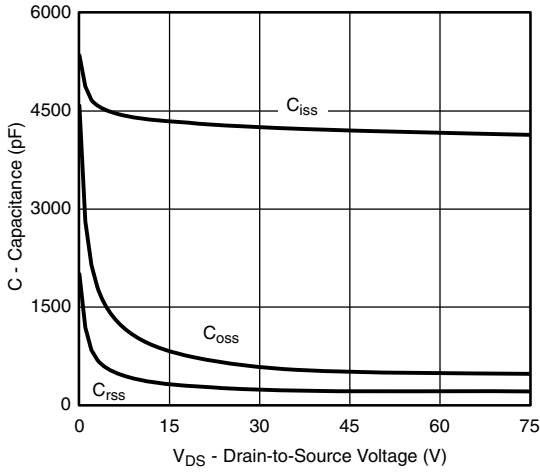
**On-Resistance vs. Gate-to-Source Voltage**

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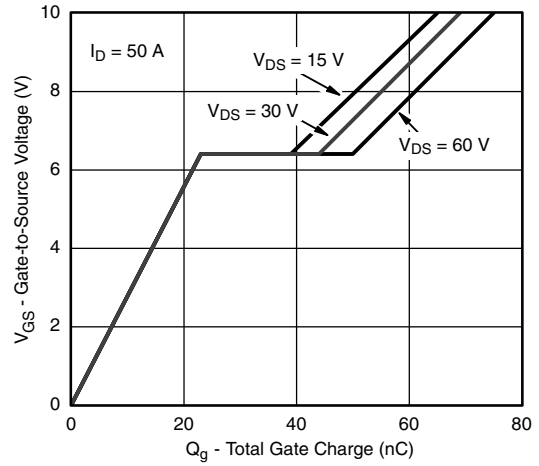
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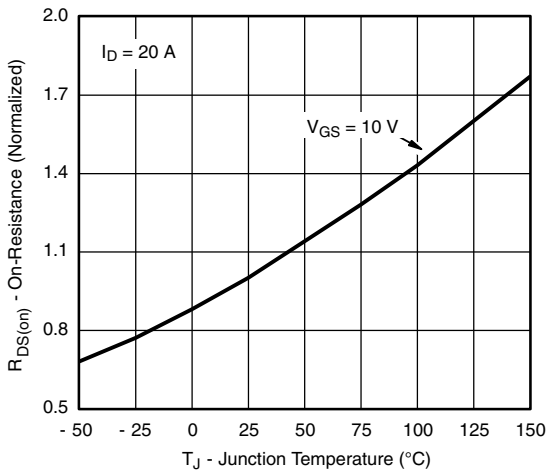
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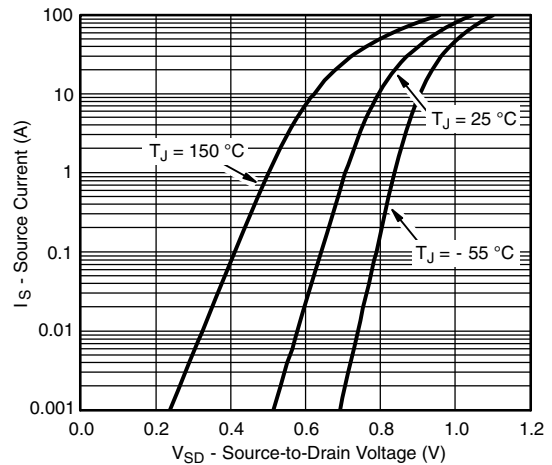
**Capacitance**



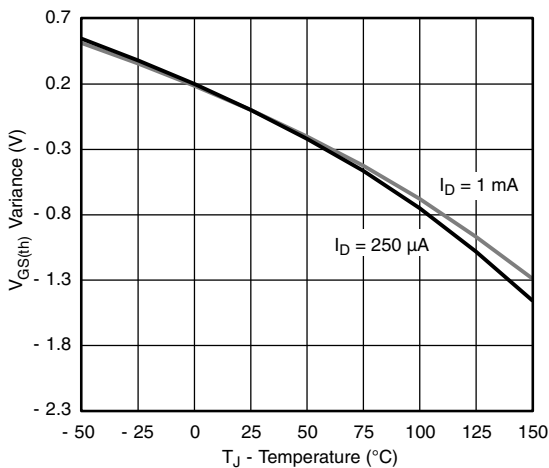
**Gate Charge**



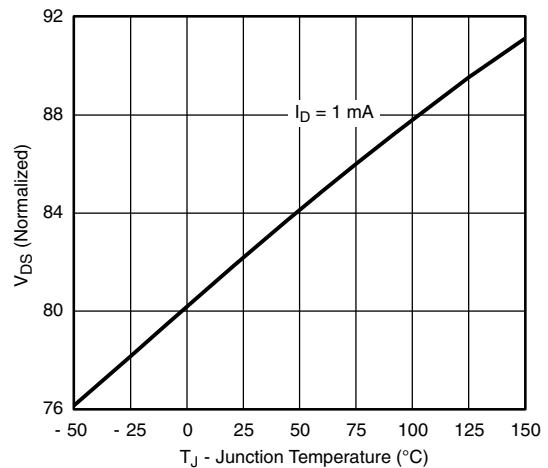
**On-Resistance vs. Junction Temperature**



**Source-Drain Diode Forward Voltage**



**Threshold Voltage**

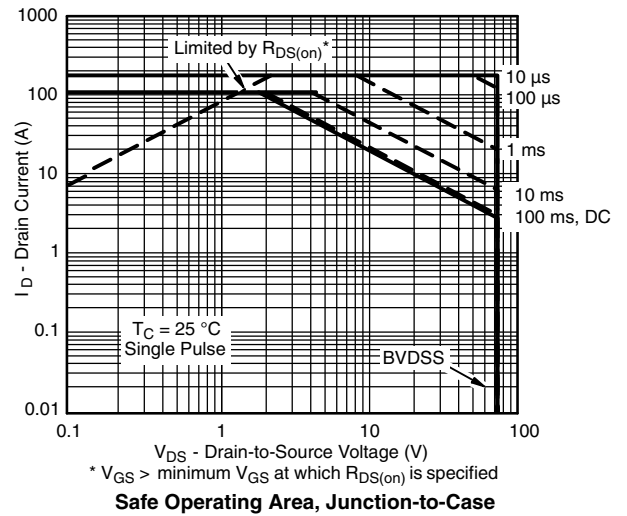
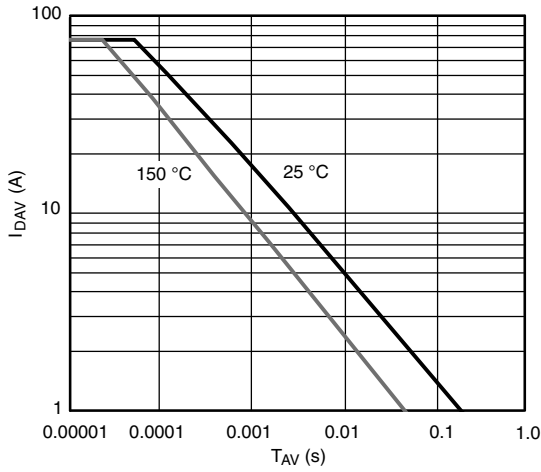


**Drain Source Breakdown vs. Junction Temperature**

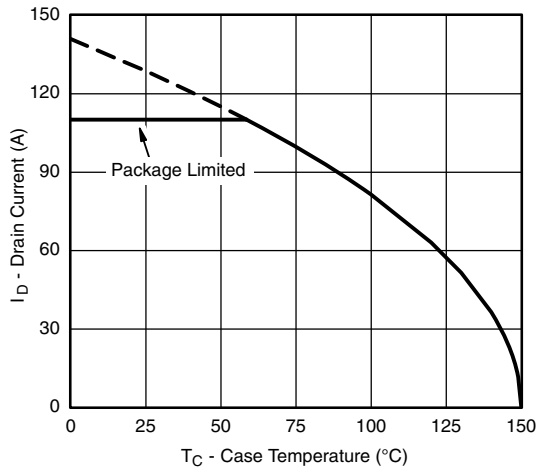


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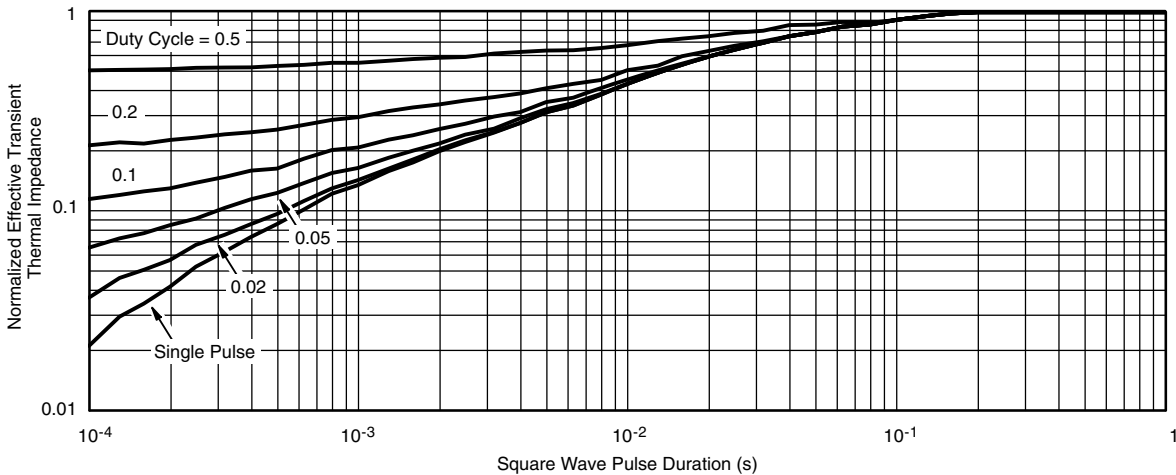


**Single Pulse Avalanche Current Capability vs. Time**



\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150\text{ °C}$ , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

**Current Derating\*, Junction-to-Case**



**Normalized Thermal Transient Impedance, Junction-to-Case**

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